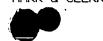
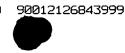
CLAIMS:

- 1. Dip soldering apparatus comprising a reservoir for solder into which component leads are dipped, wherein a surface which is wetted by the solder is provided closely adjacent to and facing the leads during dipping.
- 2. Apparatus for soldering two or more leads to a circuit board, the apparatus including molten solder and the leads being dipped into the molten solder to solder them to the circuit board, wherein a surface which is wetted by the solder is provided in the molten solder in the vicinity of the dipped leads.
- 3. Dip soldering apparatus comprising a nozzle through which solder is flowed in use, leads to be soldered being dipped into the solder surface at the nozzle outlet, wherein a surface which is wetted by the solder is provided in the solder t the nozzle outlet.
- 4. Apparatus as claimed in claim 3, wherein the wetted surface is provided by a member which is below the level of the solder surface as the solder flows through the nozzle outlet.
- 5. Apparatus as claimed in claim 3, wherein the surface is provided by a member which is movable relative to the solder surface.

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- A method of dip soldering a plurality of closely spaced leads 6. to a circuit board, the leads projecting from an underside of the board, the method comprising dipping the leads into a surface of molten solder to coat the leads and an adjacent circuit track with solder and withdrawing the leads from the solder surface, wherein a surface which is wetted by the molten solder is provided adjacent the leads, the wetted surface projecting through the solder surface as the leads are withdrawn from the solder.
- A method as claimed in claim 6, wherein the solder surface 7. is lowered to effect withdrawal of the leads from the solder.